PCN Number: 20210108000.2						PCN Date:			Jan 11, 2021			
Title	e: Adding	TI CDAT	as additi	onal	Test si	te						
Cus	tomer Cont	act: PCI	N Manager		Dept:		Quality S	ervi	ices	5		
Proposed 1 st Ship Date: Jul 11			, 2021		Estimated Sample				Date provided at			
				1, 2021		A	Availability:			sample request		
Change Type:												
	Assembly Site				Design				Wafer Bump Site			
	Assembly Process				Data Sheet				Wafer Bump Material			
Assembly Materials					Part number change				Wafer Bump Process			
	Mechanical Specification			Test Site				Wafer Fab Site Wafer Fab Materials				
Packing/Shipping/Labeling				_ Test Process				Wafer Fab Process				
PCN Details												
Description of Change: Texas Instruments Incorporated has qualified TI CDAT as an additional Test site for the devices												
listed below to support high volume ramps.												
				Current			New					
	Test Site			TI TAI			TI CDAT					
Test coverage, insertions, conditions will remain consistent with current testing.												
Reason for Change:												
Enable additional Test capacity to support high volume ramps.												
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):												
None												
	Anticipated impact on Material Declaration											
	No Impact to the Material Declarations or Product Content reports are drive from production data and will be available following the											
				roduction release. Upon production release the revised								
				eports can be obtained at the site link below								
				tp://www.ti.com/quality/docs/materialcontentsearch.tsp								
Changes to product identification resulting from this PCN:												
None												
Product Affected:												
			CMCDCO		(0.0.1		46240007		、 1			
PC	PCM6240QRTVRQ1 PCM6260QRTVRQ1 PCM6340QRTVRQ1 PCM6360QRTVRQ1											

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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